	Tito	Coard Movt	DB	Time stamp
L	Hits	Search Text	DB	Time Scattle
Number 1	27321	electrophoretic\$4	USPAT;	2002/08/15
1	2/321	Cicotiophorocity	US-PGPUB;	09:25
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	1483537	polymer\$2	USPĀT;	2002/08/15
*		F1	US-PGPUB;	09:26
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
15	157995	polymeriz\$3	USPAT;	2002/08/15
			US-PGPUB;	09:27
			EPO; JPO;	
			DERWENT;	
	2500	3	IBM_TDB	2002/08/15
22	2520	electrophoretic\$4 same polymer\$2	USPAT; US-PGPUB;	2002/08/15
			EPO; JPO;	09.26
			DERWENT;	
			IBM TDB	
29	1769	electrophoretic\$4 with polymer\$2	USPAT;	2002/08/15
1 4 3	1,09	crossrophorestoy: wrom porymerys	US-PGPUB;	09:28
-			EPO; JPO;	
			DERWENT;	
			IBM TDB	
36	42	(electrophoretic\$4 with polymer\$2) same	USPĀT;	2002/08/15
		polymeriz\$3	US-PGPUB;	09:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	444	(electrophoretic\$4 with polymer\$2) and	USPAT;	2002/08/15
		(polymeriz\$3 or cure or curing)	US-PGPUB;	09:37
			EPO; JPO;	l
İ			DERWENT; IBM TDB	
50	314	((electrophoretic\$4 with polymer\$2) and	USPAT;	2002/08/15
30	314	(polymeriz\$3 or cure or curing)) and	US-PGPUB;	09:37
		metal	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
59	1469	(gold or au or nickel or ni or tin or sn	USPAT;	2002/08/15
	1	or platinum or pt or cr or chromium) with	US-PGPUB;	10:30
		(sputter\$ and electroplat\$3)	EPO; JPO;	
İ			DERWENT;	
1			IBM_TDB	2002/00/15
66	1221	(cu or copper) with (sputter\$ and	USPAT;	2002/08/15
1		electroplat\$3)	US-PGPUB;	10:30
			EPO; JPO; DERWENT;	
			IBM TDB	
80	573	(cu or copper) with (sputter\$ with	USPAT;	2002/08/15
00	5/3	electroplat\$3)	US-PGPUB;	10:31
		crootopiacys,	EPO; JPO;	
			DERWENT;	
1			IBM TDB	
73	683	(gold or au or nickel or ni or tin or sn	USPAT;	2002/08/15
		or platinum or pt or cr or chromium) with	US-PGPUB;	10:31
		(sputter\$ with electroplat\$3)	EPO; JPO;	·
		<u> </u>	DERWENT;	
	1		IBM_TDB	
87	199		USPAT;	2002/08/15
		electroplat\$3)) with ((gold or au or	US-PGPUB;	10:32
	1	nickel or ni or tin or sn or platinum or	EPO; JPO;	
		pt or cr or chromium) with (sputter\$ with	DERWENT;	
İ	1	electroplat\$3))	IBM TDB	

		•	
94	1 (((cu or copper) with (sputter\$ with	USPAT;	2002/08/15
	electroplat\$3)) with ((gold or au or	US-PGPUB;	10:32
	nickel or ni or tin or sn or platinum or	EPO; JPO;	İ
	pt or cr or chromium) with (sputter\$ with	DERWENT;	
	electroplat\$3))) and electrophoretic\$4	IBM TDB	

Search History 8/15/02 10:34:47 AM Page 2